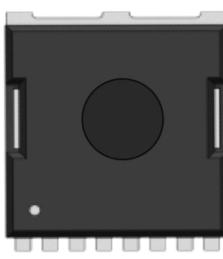


N-Channel Enhancement Mode Power MOSFET

| | |
|---|---|
| <p>Description</p> <p>The GT023N10TL uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.</p> <p>General Features</p> <ul style="list-style-type: none"> • V_{DS} 100V • I_D (at $V_{GS} = 10V$) 330A • $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 1.9mΩ • 100% Avalanche Tested • RoHS Compliant <p>Application</p> <ul style="list-style-type: none"> • Power switch • DC/DC converters |  <p>Schematic diagram</p>  <p>D G₁ S₂ S₃ S₄ S₅ S₆ S₇ S₈ TOLL-8L</p> |
|---|---|

Ordering Information

| Device | Package | Marking | Packaging |
|------------|---------|----------|--------------|
| GT023N10TL | TOLL-8L | GT023N10 | 2000pcs/Reel |

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

| Parameter | Symbol | Value | Unit |
|--|----------------|------------|------|
| Drain-Source Voltage | V_{DS} | 100 | V |
| Continuous Drain Current | I_D | 330 | A |
| Pulsed Drain Current (note1) | I_{DM} | 1320 | A |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Power Dissipation | P_D | 395 | W |
| Single pulse avalanche energy (note2) | E_{AS} | 600 | mJ |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -55 To 175 | °C |

Thermal Resistance

| Parameter | Symbol | Value | Unit |
|---|------------|-------|------|
| Thermal Resistance, Junction-to-Ambient | R_{thJA} | 62 | °C/W |
| Maximum Junction-to-Case | R_{thJC} | 0.32 | °C/W |

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

| Parameter | Symbol | Test Conditions | Value | | | Unit |
|--|-----------------------------|--|-------|------|-----------|------------------|
| | | | Min. | Typ. | Max. | |
| Static Parameters | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(\text{BR})\text{DSS}}$ | $V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$ | 100 | -- | -- | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$ | -- | -- | 1 | μA |
| Gate-Source Leakage | I_{GSS} | $V_{\text{GS}} = \pm 20\text{V}$ | -- | -- | ± 100 | nA |
| Gate-Source Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$ | 2.0 | 3.0 | 4.0 | V |
| Drain-Source On-Resistance | $R_{\text{DS}(\text{on})}$ | $V_{\text{GS}} = 10\text{V}, I_D = 80\text{A}$ | -- | 1.6 | 1.9 | $\text{m}\Omega$ |
| Forward Transconductance | g_{FS} | $V_{\text{GS}} = 5\text{V}, I_D = 80\text{A}$ | -- | 139 | -- | S |
| Dynamic Parameters | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 50\text{V}, f = 0.3\text{MHz}$ | -- | 8747 | -- | pF |
| Output Capacitance | C_{oss} | | -- | 2718 | -- | |
| Reverse Transfer Capacitance | C_{rss} | | -- | 32 | -- | |
| Total Gate Charge | Q_g | $V_{\text{DD}} = 50\text{V}, I_D = 80\text{A}, V_{\text{GS}} = 10\text{V}$ | -- | 121 | -- | nC |
| Gate-Source Charge | Q_{gs} | | -- | 36 | -- | |
| Gate-Drain Charge | Q_{gd} | | -- | 26 | -- | |
| Turn-on Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}} = 50\text{V}, I_D = 80\text{A}, R_G = 5\Omega$ | -- | 24 | -- | ns |
| Turn-on Rise Time | t_r | | -- | 30 | -- | |
| Turn-off Delay Time | $t_{\text{d}(\text{off})}$ | | -- | 94 | -- | |
| Turn-off Fall Time | t_f | | -- | 74 | -- | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Body Diode Current | I_S | $T_C = 25^\circ\text{C}$ | -- | -- | 330 | A |
| Body Diode Voltage | V_{SD} | $T_J = 25^\circ\text{C}, I_{\text{SD}} = 80\text{A}, V_{\text{GS}} = 0\text{V}$ | -- | -- | 1.2 | V |
| Reverse Recovery Charge | Q_{rr} | $I_F = 80\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A}/\mu\text{s}$ | -- | 297 | -- | nC |
| Reverse Recovery Time | T_{rr} | | -- | 94 | -- | ns |

Notes

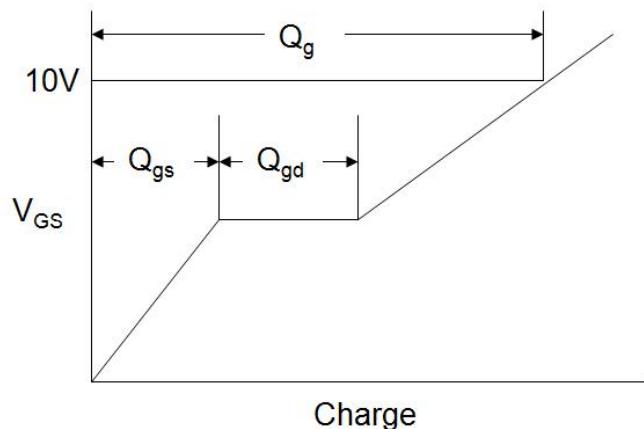
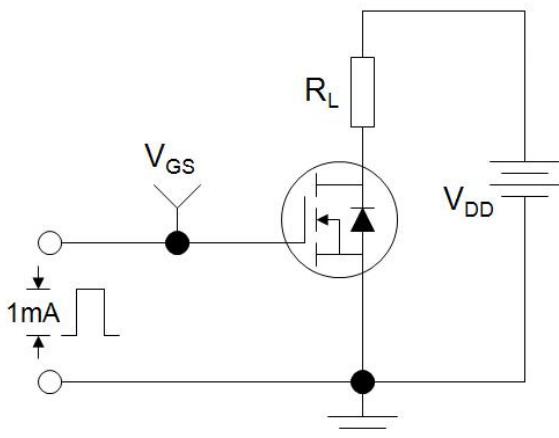
1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$

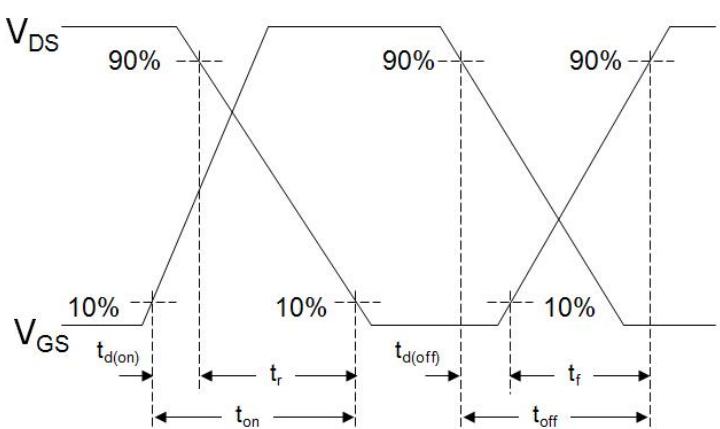
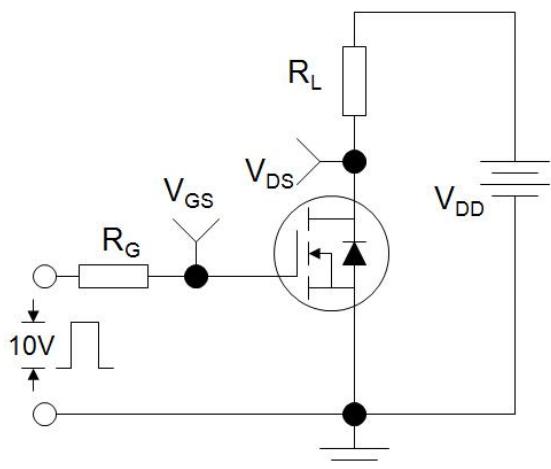
The table shows the minimum avalanche energy, which is 1600mJ when the device is tested until failure

3. Identical low side and high side switch with identical R_G

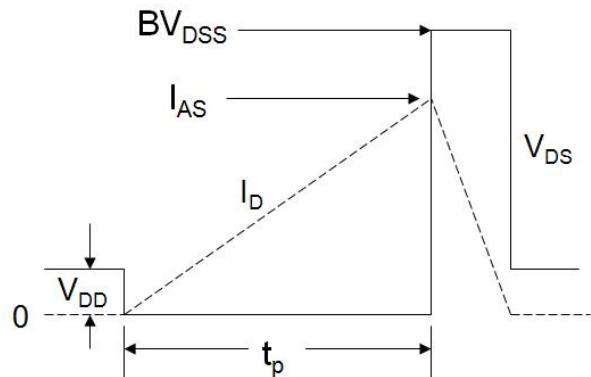
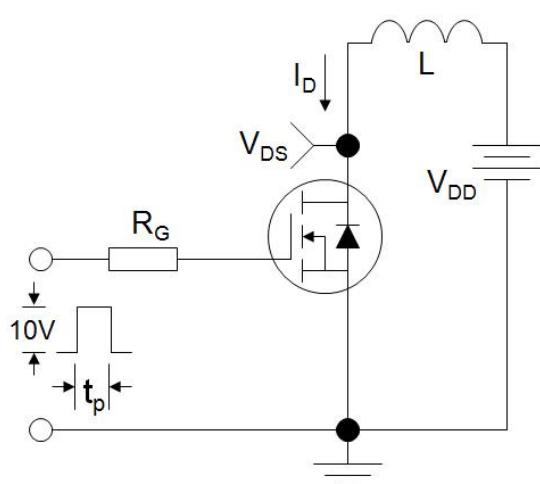
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

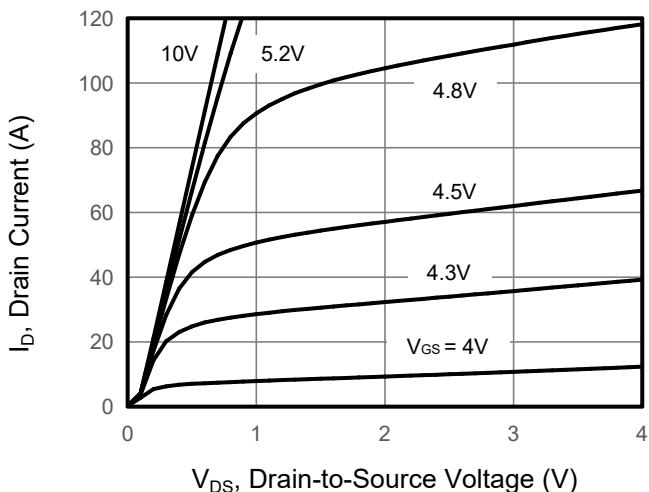


Figure 2. Transfer Characteristics

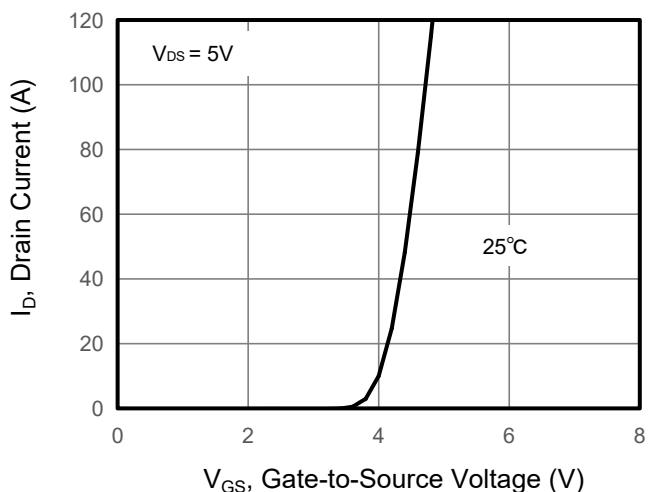


Figure 3. Drain Source On Resistance

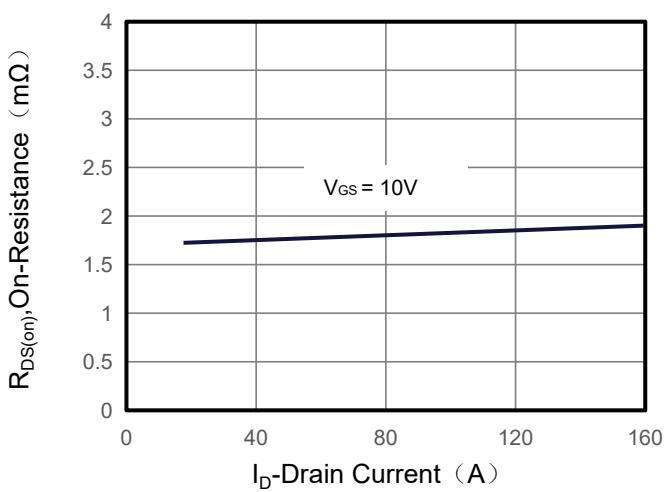


Figure 4. Gate Charge

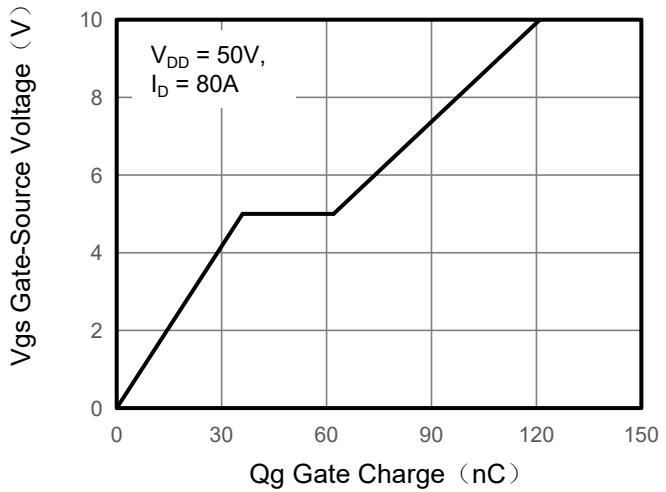


Figure 5. Capacitance

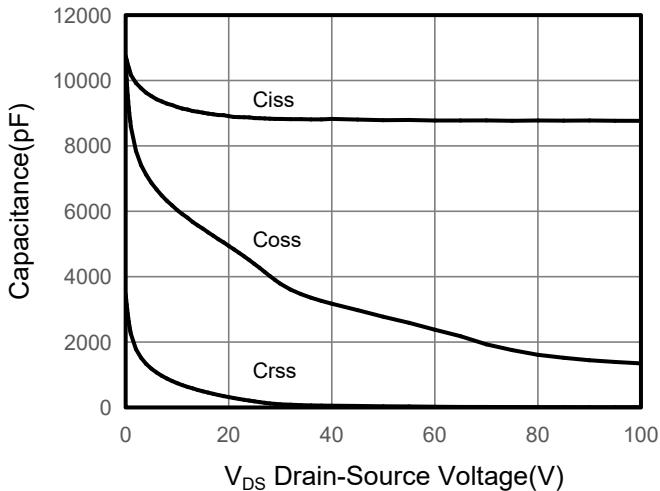
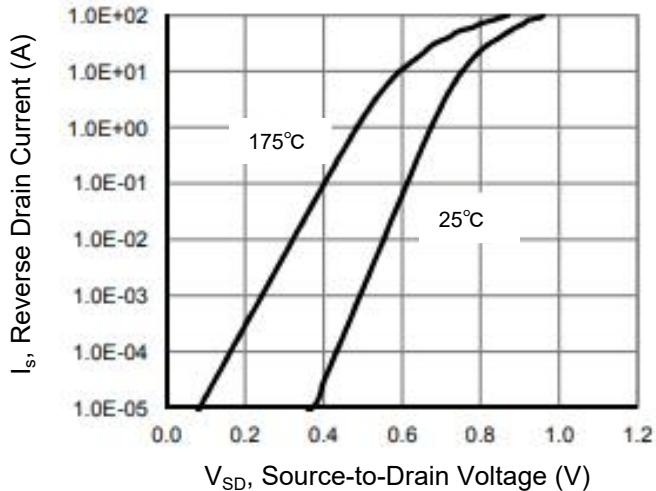


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

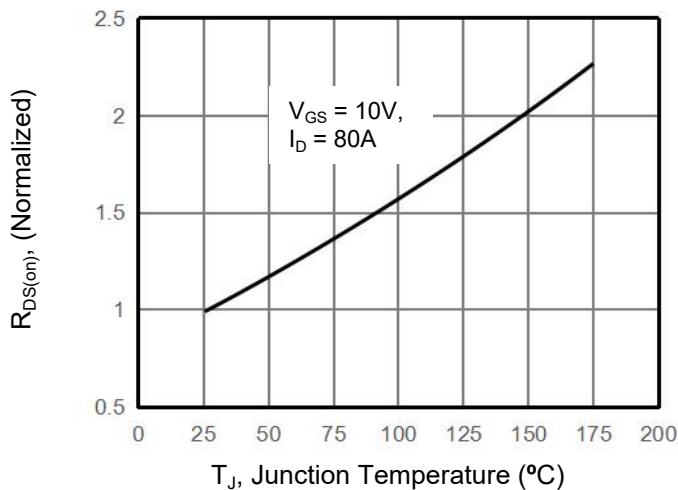


Figure 8. Safe Operation Area

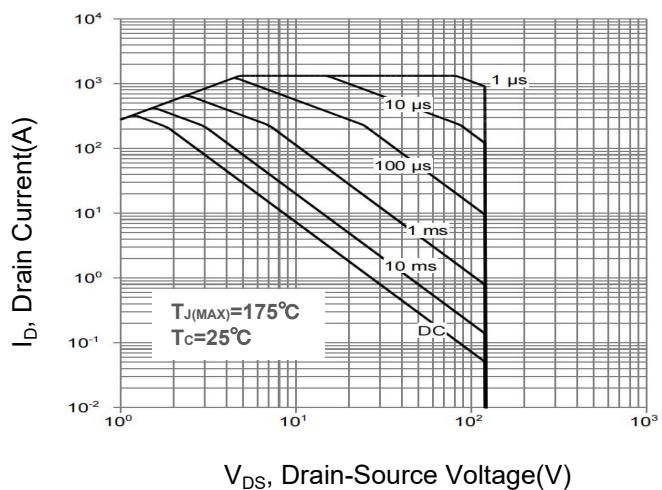
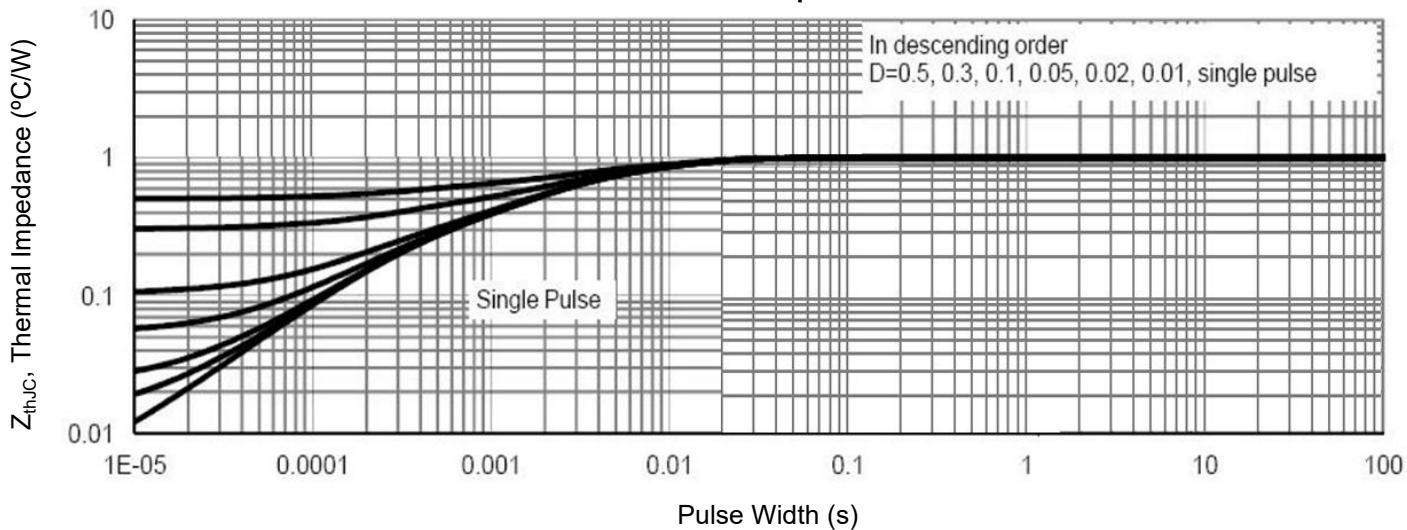
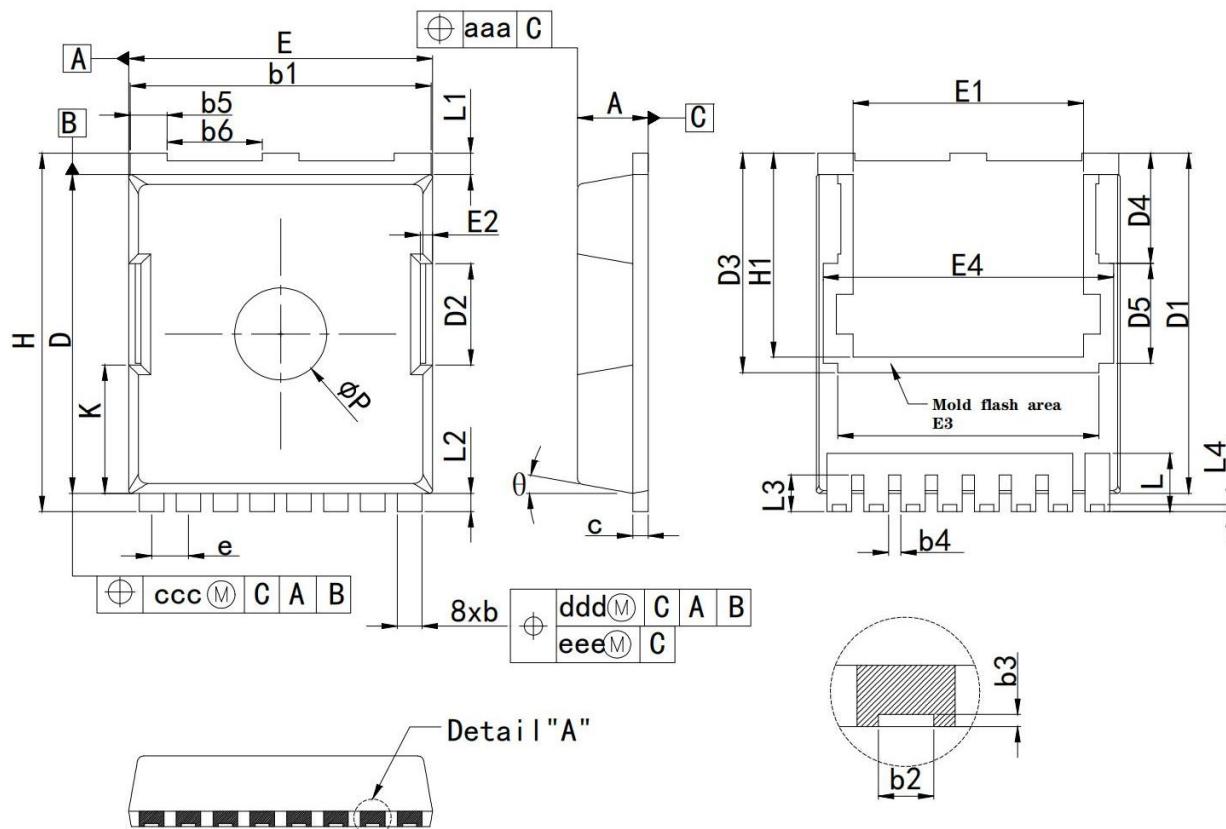


Figure 9. Normalized Maximum Transient Thermal Impedance



TOLL-8L Package Information



| SYMBOL | COMMON | | |
|----------|------------|---------|-------|
| | MILLIMETER | | |
| | MIN | NOMINAL | MAX |
| A | 2.20 | 2.30 | 2.40 |
| b | 0.70 | 0.80 | 0.90 |
| b1 | 9.70 | 9.80 | 9.90 |
| b2 | 0.36 | 0.45 | 0.55 |
| b3 | 0.05 | 0.100 | / |
| b4 | 0.30 | 0.40 | 0.50 |
| b5 | 1.10 | 1.20 | 1.30 |
| b6 | 3.00 | 3.10 | 3.20 |
| c | 0.40 | 0.50 | 0.60 |
| D | 10.28 | 10.38 | 10.55 |
| D1 | 10.98 | 11.08 | 11.18 |
| D2 | 3.20 | 3.30 | 3.40 |
| D3 | 7.15 | | |
| D4 | 3.59 | | |
| D5 | 3.26 | | |
| e | 1.10 | 1.20 | 1.30 |
| E | 9.80 | 9.90 | 10.00 |
| E1 | 7.40 | 7.50 | 7.60 |
| E2 | 0.30 | 0.40 | 0.50 |
| E3 | | 8.50 | |
| E4 | | 9.46 | |
| H | 11.50 | 11.68 | 11.85 |
| H1 | 6.55 | 6.65 | 6.75 |
| K | 4.08 | 4.18 | 4.28 |
| L | 1.60 | 1.90 | 2.10 |
| L1 | 0.50 | 0.70 | 0.90 |
| L2 | 0.50 | 0.60 | 0.70 |
| L3 | 1.00 | 1.20 | 1.30 |
| L4 | 0.13 | 0.23 | 0.33 |
| P | 2.85 | 3.00 | 3.15 |
| θ | 10°REF | | |
| aaa | 0.20 | | |
| ccc | 0.20 | | |
| ddd | 0.25 | | |
| eee | 0.20 | | |